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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	69
Number of Gates	6000
Voltage - Supply	3V ~ 3.6V, 4.75V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	80-TQFP
Supplier Device Package	80-VQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a40mx04-vq80



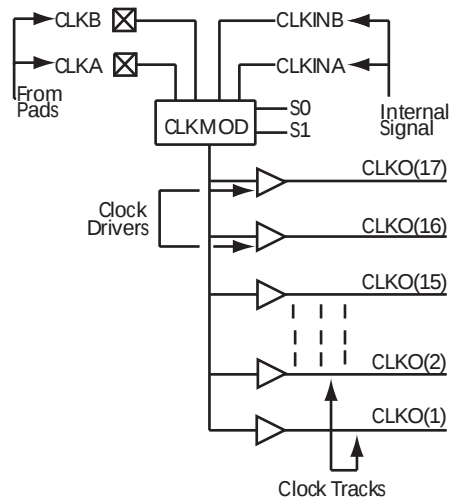
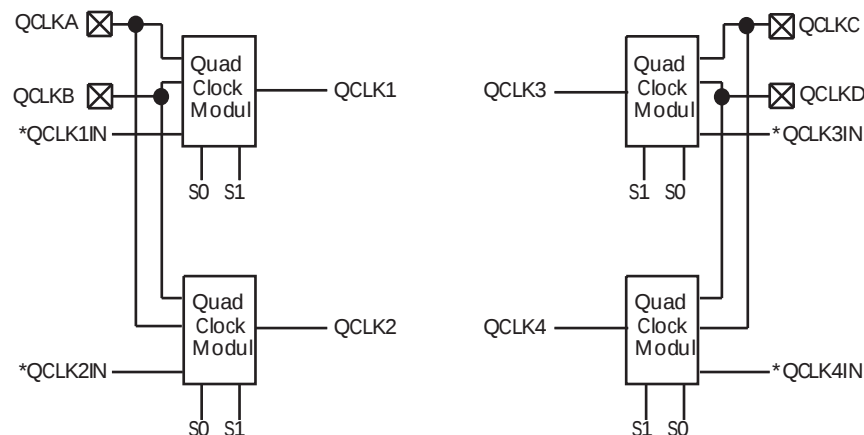
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Figure 8 • Clock Networks of 42MX Devices**Figure 9 • Quadrant Clock Network of A42MX36 Devices**

Note: *QCLK1IN, QCLK2IN, QCLK3IN, and QCLK4IN are internally-generated signals.

3.2.5 MultiPlex I/O Modules

42MX devices feature Multiplex I/Os and support 5.0 V, 3.3 V, and mixed 3.3 V/5.0 V operations.

The MultiPlex I/O modules provide the interface between the device pins and the logic array. [Figure 10](#), page 12 is a block diagram of the 42MX I/O module. A variety of user functions, determined by a library macro selection, can be implemented in the module. (See the [Antifuse Macro Library Guide](#) for more information.) All 42MX I/O modules contain tristate buffers, with input and output latches that can be configured for input, output, or bidirectional operation.

All 42MX devices contain flexible I/O structures, where each output pin has a dedicated output-enable control ([Figure 10](#), page 12). The I/O module can be used to latch input or output data, or both, providing fast set-up time. In addition, the Designer software tools can build a D-type flip-flop using a C-module combined with an I/O module to register input and output signals. See the [Antifuse Macro Library Guide](#) for more details.

A42MX24 and A42MX36 devices also offer selectable PCI output drives, enabling 100% compliance with version 2.1 of the PCI specification. For low-power systems, all inputs and outputs are turned off to reduce current consumption to below 500 μ A.

To achieve 5.0 V or 3.3 V PCI-compliant output drives on A42MX24 and A42MX36 devices, a chip-wide PCI fuse is programmed via the Device Selection Wizard in the Designer software ([Figure 11](#), page 12). When the PCI fuse is not programmed, the output drive is standard.

f_{q2} = Average second routed array clock rate in MHz)

Table 7 • Fixed Capacitance Values for MX FPGAs (pF)

Device Type	r1 routed_Clk1	r2 routed_Clk2
A40MX02	41.4	N/A
A40MX04	68.6	N/A
A42MX09	118	118
A42MX16	165	165
A42MX24	185	185
A42MX36	220	220

3.4.6 Test Circuitry and Silicon Explorer II Probe

MX devices contain probing circuitry that provides built-in access to every node in a design, via the use of Silicon Explorer II. Silicon Explorer II is an integrated hardware and software solution that, in conjunction with the Designer software, allow users to examine any of the internal nets of the device while it is operating in a prototyping or a production system. The user can probe into an MX device without changing the placement and routing of the design and without using any additional resources. Silicon Explorer II's noninvasive method does not alter timing or loading effects, thus shortening the debug cycle and providing a true representation of the device under actual functional situations.

Silicon Explorer II samples data at 100 MHz (asynchronous) or 66 MHz (synchronous). Silicon Explorer II attaches to a PC's standard COM port, turning the PC into a fully functional 18-channel logic analyzer. Silicon Explorer II allows designers to complete the design verification process at their desks and reduces verification time from several hours per cycle to a few seconds.

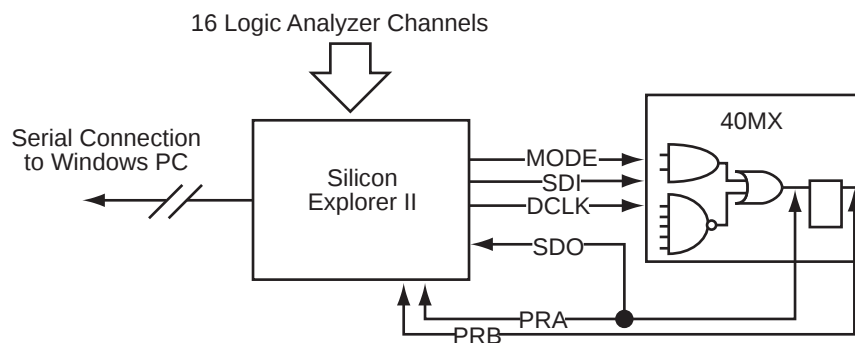
Silicon Explorer II is used to control the MODE, DCLK, SDI and SDO pins in MX devices to select the desired nets for debugging. The user simply assigns the selected internal nets in the Silicon Explorer II software to the PRA/PRB output pins for observation. Probing functionality is activated when the MODE pin is held HIGH.

Figure 12, page 16 illustrates the interconnection between Silicon Explorer II and 40MX devices, while Figure 13, page 17 illustrates the interconnection between Silicon Explorer II and 42MX devices

To allow for probing capabilities, the security fuses must not be programmed. (See [User Security](#), page 12 for the security fuses of 40MX and 42MX devices). Table 8, page 17 summarizes the possible device configurations for probing.

PRA and PRB pins are dual-purpose pins. When the "Reserve Probe Pin" is checked in the Designer software, PRA and PRB pins are reserved as dedicated outputs for probing. If PRA and PRB pins are required as user I/Os to achieve successful layout and "Reserve Probe Pin" is checked, the layout tool will override the option and place user I/Os on PRA and PRB pins.

Figure 12 • Silicon Explorer II Setup with 40MX



3.9.1 Mixed 5.0V/3.3V Electrical Specifications

Table 22 • Mixed 5.0V/3.3V Electrical Specifications

Symbol	Parameter	Commercial		Commercial –F		Industrial		Military		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
VOH ¹	IOH = –10 mA	2.4		2.4						V
	IOH = –4 mA					2.4		2.4		V
VOL ¹	IOL = 10 mA	0.5		0.5						V
	IOL = 6 mA					0.4		0.4		V
VIL		–0.3	0.8	–0.3	0.8	–0.3	0.8	–0.3	0.8	V
VIH ²		2.0	VCCA + 0.3	2.0	VCCA + 0.3	2.0	VCCA + 0.3	2.0	VCCA + 0.3	V
IL	VIN = 0.5 V	–10		–10		–10		–10		μA
IH	VIN = 2.7 V	–10		–10		–10		–10		μA
Input Transition Time, TR and TF		500		500		500		500		ns
C _{IO} I/O Capacitance		10		10		10		10		pF
Standby Current, ICC ³	A42MX09	5		25		25		25		mA
	A42MX16	6		25		25		25		mA
	A42MX24, A42MX36	20		25		25		25		mA
Low Power Mode Standby Current		0.5		ICC – 5.0		ICC – 5.0		ICC – 5.0		mA
I/O I/O source sink current Can be derived from the <i>IBIS model</i> (http://www.microsemi.com/soc/techdocs/models/ibis.html)										

1. Only one output tested at a time. VCCI = min.

2. VIH(Min) is 2.4V for A42MX36 family. This applies only to VCCI of 5V and is not applicable to VCCI of 3.3V

3. All outputs unloaded. All inputs = VCCI or GND

3.9.2 Output Drive Characteristics for 5.0 V PCI Signaling

MX PCI device I/O drivers were designed specifically for high-performance PCI systems. Figure 16, page 28 shows the typical output drive characteristics of the MX devices. MX output drivers are compliant with the PCI Local Bus Specification.

Table 23 • DC Specification (5.0 V PCI Signaling)¹

Symbol	Parameter	Condition	PCI		MX		Units
			Min.	Max.	Min.	Max.	
VCCI	Supply Voltage for I/Os		4.75	5.25	4.75	5.25 ²	V
VIH ³	Input High Voltage		2.0	VCC + 0.5	2.0	VCCI + 0.3	V
VIL	Input Low Voltage		–0.5	0.8	–0.3	0.8	V
IIH	Input High Leakage Current	VIN = 2.7 V		70	—	10	μA
IIL	Input Low Leakage Current	VIN=0.5 V		–70	—	–10	μA
VOH	Output High Voltage	IOUT = –2 mA IOUT = –6 mA	2.4		3.84		V
VOL	Output Low Voltage	IOUT = 3 mA, 6 mA		0.55	—	0.33	V

Table 34 • A40MX02 Timing Characteristics (Nominal 5.0 V Operation) (continued)
 (Worst-Case Commercial Conditions, VCC = 4.75 V, T_J = 70°C)

Parameter / Description		–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
TTL Output Module Timing ⁴												
t _{DLH}	Data-to-Pad HIGH		3.3		3.8		4.3		5.1		7.2	ns
t _{DHL}	Data-to-Pad LOW		4.0		4.6		5.2		6.1		8.6	ns
t _{ENZH}	Enable Pad Z to HIGH		3.7		4.3		4.9		5.8		8.0	ns
t _{ENZL}	Enable Pad Z to LOW		4.7		5.4		6.1		7.2		10.1	ns
t _{ENHZ}	Enable Pad HIGH to Z		7.9		9.1		10.4		12.2		17.1	ns
t _{ENLZ}	Enable Pad LOW to Z		5.9		6.8		7.7		9.0		12.6	ns
d _{TLH}	Delta LOW to HIGH		0.02		0.02		0.03		0.03		0.04	ns/pF
d _{THL}	Delta HIGH to LOW		0.03		0.03		0.03		0.04		0.06	ns/pF
CMOS Output Module Timing ⁴												
t _{DLH}	Data-to-Pad HIGH		3.9		4.5		5.1		6.05		8.5	ns
t _{DHL}	Data-to-Pad LOW		3.4		3.9		4.4		5.2		7.3	ns
t _{ENZH}	Enable Pad Z to HIGH		3.4		3.9		4.4		5.2		7.3	ns
t _{ENZL}	Enable Pad Z to LOW		4.9		5.6		6.4		7.5		10.5	ns
t _{ENHZ}	Enable Pad HIGH to Z		7.9		9.1		10.4		12.2		17.0	ns
t _{ENLZ}	Enable Pad LOW to Z		5.9		6.8		7.7		9.0		12.6	ns
d _{TLH}	Delta LOW to HIGH		0.03		0.04		0.04		0.05		0.07	ns/pF
d _{THL}	Delta HIGH to LOW		0.02		0.02		0.03		0.03		0.04	ns/pF

1. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance
2. Set-up times assume fanout of 3. Further testing information can be obtained from the Timer utility
3. The hold time for the DFME1A macro may be greater than 0 ns. Use the Timer tool from the Designer software to check the hold time for this macro.
4. Delays based on 35pF loading

Table 35 • A40MX02 Timing Characteristics (Nominal 3.3 V Operation)
 (Worst-Case Commercial Conditions, VCC = 3.0 V, T_J = 70°C)

Parameter / Description		–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Logic Module Propagation Delays												
t _{PD1}	Single Module		1.7		2.0		2.3		2.7		3.7	ns
t _{PD2}	Dual-Module Macros		3.7		4.3		4.9		5.7		8.0	ns
t _{CO}	Sequential Clock-to-Q		1.7		2.0		2.3		2.7		3.7	ns
t _{GO}	Latch G-to-Q		1.7		2.0		2.3		2.7		3.7	ns
t _{RS}	Flip-Flop (Latch) Reset-to-Q		1.7		2.0		2.3		2.7		3.7	ns
Logic Module Predicted Routing Delays ¹												

Table 39 • A42MX09 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 3.0 V, T_J = 70°C)

Parameter / Description			–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Input Module Propagation Delays													
t _{INYH}	Pad-to-Y HIGH		1.5		1.6		1.8		2.17		3.0		ns
t _{INYL}	Pad-to-Y LOW		1.2		1.3		1.4		1.7		2.4		ns
t _{INGH}	G to Y HIGH		1.8		2.0		2.3		2.7		3.7		ns
t _{INGL}	G to Y LOW		1.8		2.0		2.3		2.7		3.7		ns
Input Module Predicted Routing Delays ²													
t _{IRD1}	FO = 1 Routing Delay		2.8		3.2		3.6		4.2		5.9		ns
t _{IRD2}	FO = 2 Routing Delay		3.2		3.5		4.0		4.7		6.6		ns
t _{IRD3}	FO = 3 Routing Delay		3.5		3.9		4.4		5.2		7.3		ns
t _{IRD4}	FO = 4 Routing Delay		3.9		4.3		4.9		5.7		8.0		ns
t _{IRD8}	FO = 8 Routing Delay		5.2		5.8		6.6		7.7		10.8		ns
Global Clock Network													
t _{CKH}	Input LOW to HIGH	FO = 32	4.1		4.5		5.1		6.0		8.4		ns
		FO = 256	4.5		5.0		5.6		6.7		9.3		ns
t _{CKL}	Input HIGH to LOW	FO = 32	5.0		5.5		6.2		7.3		10.2		ns
		FO = 256	5.4		6.0		6.8		8.0		11.2		ns
t _{PWH}	Minimum Pulse Width HIGH	FO = 32	1.7		1.9		2.1		2.5		3.5		ns
		FO = 256	1.9		2.1		2.3		2.7		3.8		ns
t _{PWL}	Minimum Pulse Width LOW	FO = 32	1.7		1.9		2.1		2.5		3.5		ns
		FO = 256	1.9		2.1		2.3		2.7		3.8		ns
t _{CKSW}	Maximum Skew	FO = 32	0.4		0.5		0.5		0.6		0.9		ns
		FO = 256	0.4		0.5		0.5		0.6		0.9		ns
t _{SUEXT}	Input Latch External Set-Up	FO = 32	0.0		0.0		0.0		0.0		0.0		ns
		FO = 256	0.0		0.0		0.0		0.0		0.0		ns
t _{HEXT}	Input Latch External Hold	FO = 32	3.3		3.7		4.2		4.9		6.9		ns
		FO = 256	3.7		4.1		4.6		5.5		7.6		ns
t _P	Minimum Period	FO = 32	5.6		6.2		6.7		7.8		12.9		ns
		FO = 256	6.1		6.8		7.4		8.5		14.2		ns
f _{MAX}	Maximum Frequency	FO = 32	177		161		148		129		77		MHz
		FO = 256	161		146		135		117		70		MHz

Table 40 • A42MX16 Timing Characteristics (Nominal 5.0 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 4.75 V, T_J = 70°C)

Parameter / Description			–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PWL}	Minimum Pulse Width LOW	FO = 32	3.2		3.5		4.0		4.7		6.6		ns
		FO = 384	3.7		4.1		4.6		5.4		7.6		ns
t _{CKSW}	Maximum Skew	FO = 32		0.3		0.4		0.4		0.5		0.7	ns
		FO = 384		0.3		0.4		0.4		0.5		0.7	ns
t _{SUEXT}	Input Latch External Set-Up	FO = 32	0.0		0.0		0.0		0.0		0.0		ns
		FO = 384	0.0		0.0		0.0		0.0		0.0		ns
t _{HEXT}	Input Latch External Hold	FO = 32	2.8		3.1		5.5		4.1		5.7		ns
		FO = 384	3.2		3.5		4.0		4.7		6.6		ns
t _P	Minimum Period	FO = 32	4.2		4.67		5.1		5.8		9.7		ns
		FO = 384	4.6		5.1		5.6		6.4		10.7		ns
f _{MAX}	Maximum Frequency	FO = 32		237		215		198		172		103	MHz
		FO = 384		215		195		179		156		94	MHz

Table 41 • A42MX16 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 3.0 V, T_J = 70°C)

Parameter / Description			-3 Speed		-2 Speed		-1 Speed		Std Speed		-F Speed		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PWL}	Minimum Pulse Width LOW	FO = 32 FO = 384	5.3 6.2		5.9 6.9		6.7 7.9		7.8 9.2		11.0 12.9		ns ns
t _{CKSW}	Maximum Skew	FO = 32 FO = 384		0.5 2.2		0.5 2.4		0.6 2.7		0.7 3.2		1.0 4.5	ns ns
t _{SUEXT}	Input Latch External Set-Up	FO = 32 FO = 384	0.0 0.0		0.0 0.0		0.0 0.0		0.0 0.0		0.0 0.0		ns ns
t _{HEXT}	Input Latch External Hold	FO = 32 FO = 384	3.9 4.5		4.3 4.9		4.9 5.6		5.7 6.6		8.0 9.2		ns ns
t _p	Minimum Period	FO = 32 FO = 384	7.0 7.7		7.8 8.6		8.4 9.3		9.7 10.7		16.2 17.8		ns ns
f _{MAX}	Maximum Frequency	FO = 32 FO = 384		142 129		129 117		119 108		103 94		62 56	MHz MHz
TTL Output Module Timing⁵													
t _{DLH}	Data-to-Pad HIGH			3.5		3.9		4.4		5.2		7.3	ns
t _{DHL}	Data-to-Pad LOW			4.1		4.6		5.2		6.1		8.6	ns
t _{ENZH}	Enable Pad Z to HIGH			3.8		4.2		4.8		5.6		7.8	ns
t _{ENZL}	Enable Pad Z to LOW			4.2		4.6		5.3		6.2		8.7	ns
t _{ENHZ}	Enable Pad HIGH to Z			7.6		8.4		9.5		11.2		15.7	ns
t _{ENLZ}	Enable Pad LOW to Z			7.0		7.8		8.8		10.4		14.5	ns
t _{GLH}	G-to-Pad HIGH			4.8		5.3		6.0		7.2		10.0	ns
t _{GHL}	G-to-Pad LOW			4.8		5.3		6.0		7.2		10.0	ns
t _{LCO}	I/O Latch Clock-to-Out (Pad-to-Pad), 64 Clock Loading			8.0		8.9		10.1		11.9		16.7	ns
t _{ACO}	Array Clock-to-Out (Pad-to-Pad), 64 Clock Loading			11.3		12.5		14.2		16.7		23.3	ns
d _{TLH}	Capacitive Loading, LOW to HIGH			0.04		0.04		0.05		0.06		0.08	ns/pF
d _{THL}	Capacitive Loading, HIGH to LOW			0.05		0.05		0.06		0.07		0.10	ns/pF
CMOS Output Module Timing⁵													
t _{DLH}	Data-to-Pad HIGH			4.5		5.0		5.6		6.6		9.3	ns
t _{DHL}	Data-to-Pad LOW			3.4		3.8		4.3		5.1		7.1	ns
t _{ENZH}	Enable Pad Z to HIGH			3.8		4.2		4.8		5.6		7.8	ns
t _{ENZL}	Enable Pad Z to LOW			4.2		4.6		5.3		6.2		8.7	ns
t _{ENHZ}	Enable Pad HIGH to Z			7.6		8.4		9.5		11.2		15.7	ns
t _{ENLZ}	Enable Pad LOW to Z			7.0		7.8		8.8		10.4		14.5	ns
t _{GLH}	G-to-Pad HIGH			7.1		7.9		8.9		10.5		14.7	ns
t _{GHL}	G-to-Pad LOW			7.1		7.9		8.9		10.5		14.7	ns
t _{LCO}	I/O Latch Clock-to-Out (Pad-to-Pad), 64 Clock Loading			8.0		8.9		10.1		11.9		16.7	ns

Table 43 • A42MX24 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 3.0 V, T_J = 70°C)

Parameter / Description			–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Input Module Predicted Routing Delays ²													
t _{IRD1}	FO = 1 Routing Delay		2.6		2.9		3.2		3.8		5.3		ns
t _{IRD2}	FO = 2 Routing Delay		2.9		3.2		3.6		4.3		6.0		ns
t _{IRD3}	FO = 3 Routing Delay		3.2		3.6		4.0		4.8		6.6		ns
t _{IRD4}	FO = 4 Routing Delay		3.5		3.9		4.4		5.2		7.3		ns
t _{IRD8}	FO = 8 Routing Delay		4.8		5.3		6.1		7.1		10.0		ns
Global Clock Network													
t _{CKH}	Input LOW to HIGH	FO = 32	4.4		4.8		5.5		6.5		9.1		ns
		FO = 486	4.8		5.3		6.0		7.1		10.0		ns
t _{CKL}	Input HIGH to LOW	FO = 32	5.1		5.7		6.4		7.6		10.6		ns
		FO = 486	6.0		6.6		7.5		8.8		12.4		ns
t _{PWH}	Minimum Pulse Width HIGH	FO = 32	3.0		3.3		3.8		4.5		6.3		ns
		FO = 486	3.3		3.7		4.2		4.9		6.9		ns
t _{PWL}	Minimum Pulse Width LOW	FO = 32	3.0		3.4		3.8		4.5		6.3		ns
		FO = 486	3.3		3.7		4.2		4.9		6.9		ns
t _{CKSW}	Maximum Skew	FO = 32	0.8		0.8		1.0		1.1		1.6		ns
		FO = 486	0.8		0.8		1.0		1.1		1.6		ns
t _{SUEXT}	Input Latch External Set-Up	FO = 32	0.0		0.0		0.0		0.0		0.0		ns
		FO = 486	0.0		0.0		0.0		0.0		0.0		ns
TTL Output Module Timing ⁵													
t _{DLH}	Data-to-Pad HIGH		3.4		3.8		4.3		5.0		7.1		ns
t _{DHL}	Data-to-Pad LOW		4.0		4.4		5.0		5.9		8.3		ns
t _{ENZH}	Enable Pad Z to HIGH		3.6		4.0		4.5		5.3		7.4		ns
t _{ENZL}	Enable Pad Z to LOW		3.9		4.4		5.0		5.8		8.2		ns
t _{ENHZ}	Enable Pad HIGH to Z		7.2		8.0		9.1		10.7		14.9		ns
t _{ENLZ}	Enable Pad LOW to Z		6.7		7.5		8.5		9.9		13.9		ns
t _{GLH}	G-to-Pad HIGH		4.8		5.3		6.0		7.2		10.0		ns
t _{GHL}	G-to-Pad LOW		4.8		5.3		6.0		7.2		10.0		ns
t _{LSU}	I/O Latch Output Set-Up		0.7		0.7		0.8		1.0		1.4		ns

Table 45 • A42MX36 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 3.0 V, T_J = 70°C)

Parameter / Description			-3 Speed		-2 Speed		-1 Speed		Std Speed		-F Speed		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Input Module Predicted Routing Delays ²													
t _{IRD1}	FO = 1 Routing Delay		2.8		3.1		3.5		4.1		5.7		ns
t _{IRD2}	FO = 2 Routing Delay		3.2		3.5		4.1		4.8		6.7		ns
t _{IRD3}	FO = 3 Routing Delay		3.7		4.1		4.7		5.5		7.7		ns
t _{IRD4}	FO = 4 Routing Delay		4.2		4.6		5.3		6.2		8.7		ns
t _{IRD8}	FO = 8 Routing Delay		6.1		6.8		7.7		9.0		12.6		ns
Global Clock Network													
t _{CKH}	Input LOW to HIGH	FO = 32	4.6		5.1		5.7		6.7		9.3		ns
		FO = 635	5.0		5.6		6.3		7.4		10.3		ns
t _{CKL}	Input HIGH to LOW	FO = 32	5.3		5.9		6.7		7.8		11.0		ns
		FO = 635	6.8		7.6		8.6		10.1		14.1		ns
t _{PWH}	Minimum Pulse Width HIGH	FO = 32	2.5		2.7		3.1		3.6		5.1		ns
		FO = 635	2.8		3.1		3.5		4.1		5.7		ns
t _{PWL}	Minimum Pulse Width LOW	FO = 32	2.5		2.7		3.1		3.6		5.1		ns
		FO = 635	2.8		3.1		3.5		4.1		5.7		ns
t _{CKSW}	Maximum Skew	FO = 32	1.0		1.2		1.3		1.5		2.2		ns
		FO = 635	1.0		1.2		1.3		1.5		2.2		ns
t _{SUEXT}	Input Latch External Set-Up	FO = 32	0.0		0.0		0.0		0.0		0.0		ns
		FO = 635	0.0		0.0		0.0		0.0		0.0		ns
t _{HEXT}	Input Latch External Hold	FO = 32	4.0		4.4		5.0		5.9		8.2		ns
		FO = 635	4.6		5.2		5.9		6.9		9.6		ns
t _P	Minimum Period (1/f _{MAX})	FO = 32	9.2		10.2		11.1		12.7		21.2		ns
		FO = 635	9.9		11.0		12.0		13.8		23.0		ns
f _{MAX}	Maximum Datapath Frequency	FO = 32	108		98		90		79		47		MHz
		FO = 635	100		91		83		73		44		MHz
TTL Output Module Timing ⁵													
t _{DLH}	Data-to-Pad HIGH		3.6		4.0		4.5		5.3		7.4		ns
t _{DHL}	Data-to-Pad LOW		4.2		4.6		5.2		6.2		8.6		ns
t _{ENZH}	Enable Pad Z to HIGH		3.7		4.2		4.7		5.5		7.7		ns
t _{ENZL}	Enable Pad Z to LOW		4.1		4.6		5.2		6.1		8.5		ns
t _{ENHZ}	Enable Pad HIGH to Z		7.34		8.2		9.3		10.9		15.3		ns
TTL Output Module Timing ⁵													
t _{ENLZ}	Enable Pad LOW to Z		6.9		7.6		8.7		10.2		14.3		ns
t _{GLH}	G-to-Pad HIGH		4.9		5.5		6.2		7.3		10.2		ns
t _{GHL}	G-to-Pad LOW		4.9		5.5		6.2		7.3		10.2		ns
t _{LSU}	I/O Latch Output Set-Up		0.7		0.7		0.8		1.0		1.4		ns
t _{LH}	I/O Latch Output Hold		0.0		0.0		0.0		0.0		0.0		ns
t _{LCO}	I/O Latch Clock-to-Out (Pad-to-Pad) 32 I/O		7.9		8.8		10.0		11.8		16.5		ns

4 Package Pin Assignments

The following figures and tables give the details of the package pin assignments.

Figure 38 • PL44

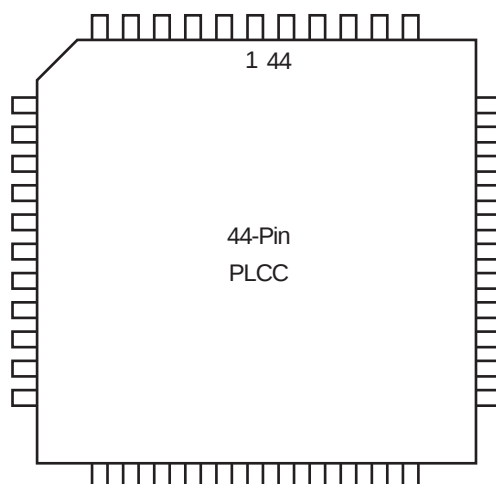


Table 47 • PL44

PL44		
Pin Number	A40MX02 Function	A40MX04 Function
1	I/O	I/O
2	I/O	I/O
3	VCC	VCC
4	I/O	I/O
5	I/O	I/O
6	I/O	I/O
7	I/O	I/O
8	I/O	I/O
9	I/O	I/O
10	GND	GND
11	I/O	I/O
12	I/O	I/O
13	I/O	I/O
14	VCC	VCC
15	I/O	I/O
16	VCC	VCC
17	I/O	I/O
18	I/O	I/O
19	I/O	I/O
20	I/O	I/O

Table 52 • PQ160

PQ160			
Pin Number	A42MX09 Function	A42MX16 Function	A42MX24 Function
58	VCCI	VCCI	VCCI
59	GND	GND	GND
60	VCCA	VCCA	VCCA
61	LP	LP	LP
62	I/O	I/O	TCK, I/O
63	I/O	I/O	I/O
64	GND	GND	GND
65	I/O	I/O	I/O
66	I/O	I/O	I/O
67	I/O	I/O	I/O
68	I/O	I/O	I/O
69	GND	GND	GND
70	NC	I/O	I/O
71	I/O	I/O	I/O
72	I/O	I/O	I/O
73	I/O	I/O	I/O
74	I/O	I/O	I/O
75	NC	I/O	I/O
76	I/O	I/O	I/O
77	NC	I/O	I/O
78	I/O	I/O	I/O
79	NC	I/O	I/O
80	GND	GND	GND
81	I/O	I/O	I/O
82	SDO, I/O	SDO, I/O	SDO, TDO, I/O
83	I/O	I/O	WD, I/O
84	I/O	I/O	WD, I/O
85	I/O	I/O	I/O
86	NC	VCCI	VCCI
87	I/O	I/O	I/O
88	I/O	I/O	WD, I/O
89	GND	GND	GND
90	NC	I/O	I/O
91	I/O	I/O	I/O
92	I/O	I/O	I/O
93	I/O	I/O	I/O
94	I/O	I/O	I/O

Table 52 • PQ160

PQ160			
Pin Number	A42MX09 Function	A42MX16 Function	A42MX24 Function
132	I/O	I/O	I/O
133	I/O	I/O	I/O
134	I/O	I/O	I/O
135	NC	VCCA	VCCA
136	I/O	I/O	I/O
137	I/O	I/O	I/O
138	NC	VCCA	VCCA
139	VCCI	VCCI	VCCI
140	GND	GND	GND
141	NC	I/O	I/O
142	I/O	I/O	I/O
143	I/O	I/O	I/O
144	I/O	I/O	I/O
145	GND	GND	GND
146	NC	I/O	I/O
147	I/O	I/O	I/O
148	I/O	I/O	I/O
149	I/O	I/O	I/O
150	NC	VCCA	VCCA
151	NC	I/O	I/O
152	NC	I/O	I/O
153	NC	I/O	I/O
154	NC	I/O	I/O
155	GND	GND	GND
156	I/O	I/O	I/O
157	I/O	I/O	I/O
158	I/O	I/O	I/O
159	MODE	MODE	MODE
160	GND	GND	GND

Table 54 • PQ240

PQ240	
Pin Number	A42MX36 Function
15	QCLKC, I/O
16	I/O
17	WD, I/O
18	WD, I/O
19	I/O
20	I/O
21	WD, I/O
22	WD, I/O
23	I/O
24	PRB, I/O
25	I/O
26	CLKB, I/O
27	I/O
28	GND
29	VCCA
30	VCCI
31	I/O
32	CLKA, I/O
33	I/O
34	PRA, I/O
35	I/O
36	I/O
37	WD, I/O
38	WD, I/O
39	I/O
40	I/O
41	I/O
42	I/O
43	I/O
44	I/O
45	QCLKD, I/O
46	I/O
47	WD, I/O
48	WD, I/O
49	I/O
50	I/O
51	I/O

Table 54 • PQ240

PQ240	
Pin Number	A42MX36 Function
200	I/O
201	I/O
202	I/O
203	I/O
204	I/O
205	I/O
206	VCCA
207	I/O
208	I/O
209	VCCA
210	VCCI
211	I/O
212	I/O
213	I/O
214	I/O
215	I/O
216	I/O
217	I/O
218	I/O
219	VCCA
220	I/O
221	I/O
222	I/O
223	I/O
224	I/O
225	I/O
226	I/O
227	VCCI
228	I/O
229	I/O
230	I/O
231	I/O
232	I/O
233	I/O
234	I/O
235	I/O
236	I/O

Table 57 • TQ176

TQ176			
Pin Number	A42MX09 Function	A42MX16 Function	A42MX24 Function
121	NC	NC	I/O
122	I/O	I/O	I/O
123	I/O	I/O	I/O
124	NC	I/O	I/O
125	NC	I/O	I/O
126	NC	NC	I/O
127	I/O	I/O	I/O
128	I/O	I/O	I/O
129	I/O	I/O	I/O
130	I/O	I/O	I/O
131	I/O	I/O	I/O
132	I/O	I/O	I/O
133	GND	GND	GND
134	I/O	I/O	I/O
135	SDI, I/O	SDI, I/O	SDI, I/O
136	NC	I/O	I/O
137	I/O	I/O	WD, I/O
138	I/O	I/O	WD, I/O
139	I/O	I/O	I/O
140	NC	VCCI	VCCI
141	I/O	I/O	I/O
142	I/O	I/O	I/O
143	NC	I/O	I/O
144	NC	I/O	WD, I/O
145	NC	NC	WD, I/O
146	I/O	I/O	I/O
147	NC	I/O	I/O
148	I/O	I/O	I/O
149	I/O	I/O	I/O
150	I/O	I/O	WD, I/O
151	NC	I/O	WD, I/O
152	PRA, I/O	PRA, I/O	PRA, I/O
153	I/O	I/O	I/O
154	CLKA, I/O	CLKA, I/O	CLKA, I/O
155	VCCA	VCCA	VCCA
156	GND	GND	GND
157	I/O	I/O	I/O

Table 58 • CQ208

CQ208	
Pin Number	A42MX36 Function
74	I/O
75	I/O
76	I/O
77	I/O
78	GND
79	VCCA
80	VCCI
81	I/O
82	I/O
83	I/O
84	I/O
85	WD, I/O
86	WD, I/O
87	I/O
88	I/O
89	I/O
90	I/O
91	QCLKB, I/O
92	I/O
93	WD, I/O
94	WD, I/O
95	I/O
96	I/O
97	I/O
98	VCCI
99	I/O
100	WD, I/O
101	WD, I/O
102	I/O
103	TDO, I/O
104	I/O
105	GND
106	VCCA
107	I/O
108	I/O
109	I/O
110	I/O

Table 59 • CQ256

CQ256	
Pin Number	A42MX36 Function
96	VCCA
97	GND
98	GND
99	I/O
100	I/O
101	I/O
102	I/O
103	I/O
104	I/O
105	WD, I/O
106	WD, I/O
107	I/O
108	I/O
109	WD, I/O
110	WD, I/O
111	I/O
112	QCLKA, I/O
113	I/O
114	GND
115	I/O
116	I/O
117	I/O
118	I/O
119	VCCI
120	I/O
121	WD, I/O
122	WD, I/O
123	I/O
124	I/O
125	I/O
126	I/O
127	GND
128	NC
129	NC
130	NC
131	GND
132	I/O

Table 60 • BG272

BG272	
Pin Number	A42MX36 Function
D20	I/O
E1	I/O
E2	I/O
E3	I/O
E4	VCCA
E17	VCCI
E18	I/O
E19	I/O
E20	I/O
F1	I/O
F2	I/O
F3	I/O
F4	VCCI
F17	I/O
F18	I/O
F19	I/O
F20	I/O
G1	I/O
G2	I/O
G3	I/O
G4	VCCI
G17	VCCI
G18	I/O
G19	I/O
G20	I/O
H1	I/O
H2	I/O
H3	I/O
H4	VCCA
H17	I/O
H18	I/O
H19	I/O
H20	I/O
J1	I/O
J2	I/O
J3	I/O
J4	VCCI

Table 60 • BG272

BG272	
Pin Number	A42MX36 Function
J9	GND
J10	GND
J11	GND
J12	GND
J17	VCCA
J18	I/O
J19	I/O
J20	I/O
K1	I/O
K2	I/O
K3	I/O
K4	VCCI
K9	GND
K10	GND
K11	GND
K12	GND
K17	I/O
K18	VCCA
K19	VCCA
K20	LP
L1	I/O
L2	I/O
L3	VCCA
L4	VCCA
L9	GND
L10	GND
L11	GND
L12	GND
L17	VCCI
L18	I/O
L19	I/O
L20	TCK, I/O
M1	I/O
M2	I/O
M3	I/O
M4	VCCI
M9	GND